

MAXWELL SERDES PCIe x2 PERSONALITY CARD

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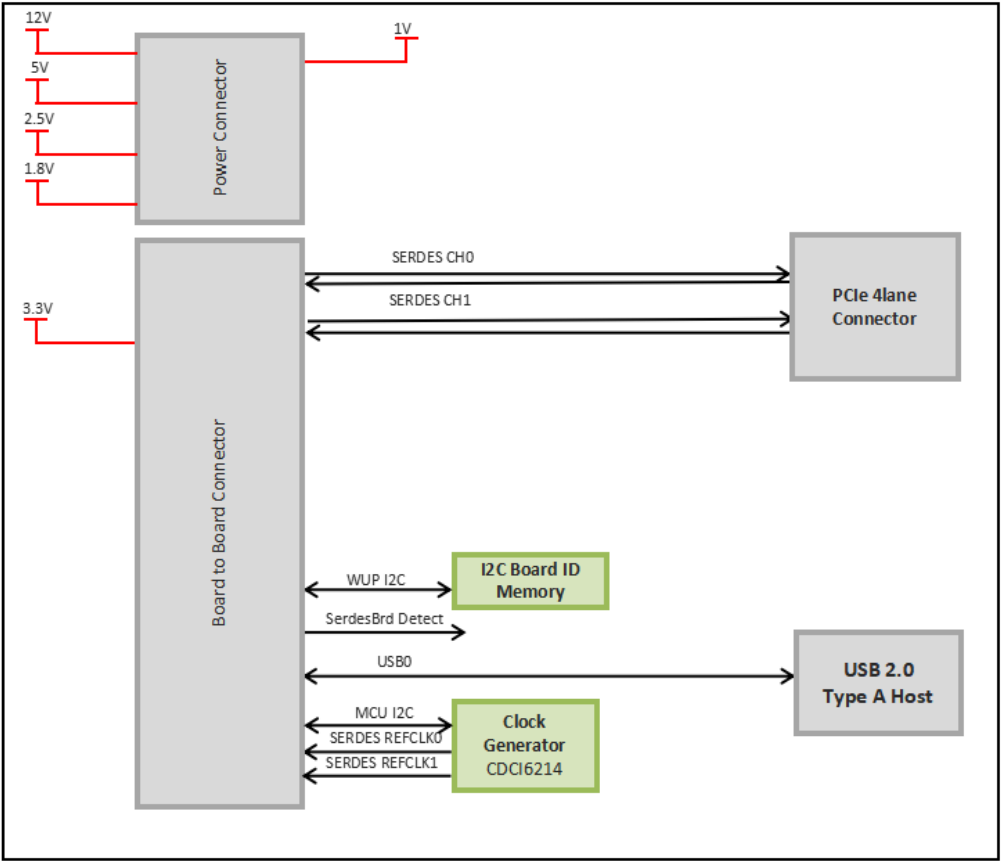
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REV	A
VER	1.0

REVISION HISTORY

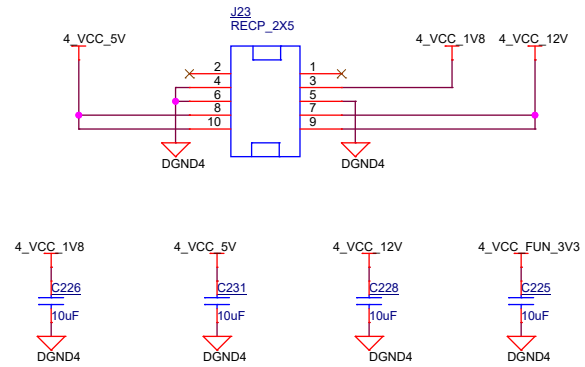
REV #	VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
A	0.1	31th JAN 2020	Drafted from Rev E3, Ver 1.0 schematics.	Mistral Design Team	AJIT MB	AJIT MB
A	0.2	31th JAN 2020	Made R247 as DNI	Mistral Design Team	AJIT MB	AJIT MB
A	0.3	20th FEB 2020	Updated alternate components	Mistral Design Team	AJIT MB	AJIT MB
A	1.0	20th MAR 2020	Baselined	Mistral Design Team	AJIT MB	AJIT MB

BLOCK DIAGRAM

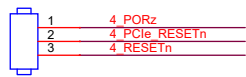
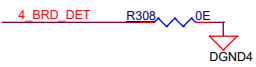
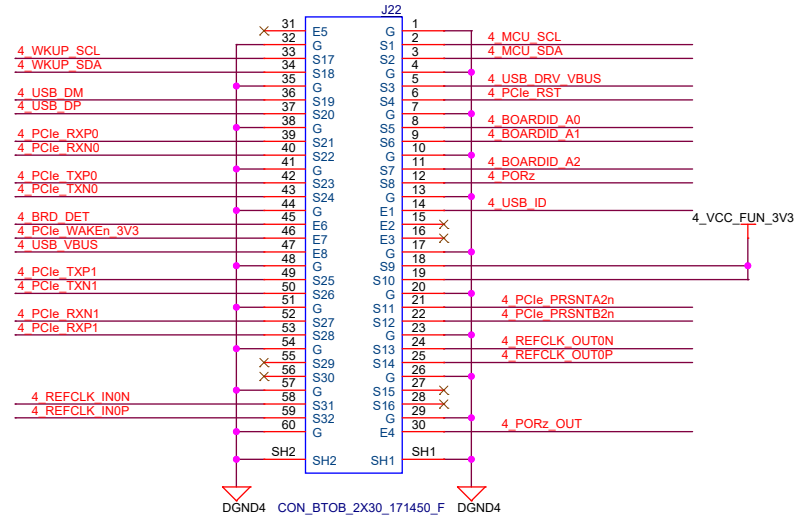
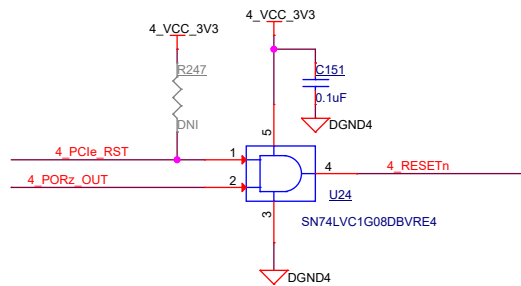


Serdes Connector

Power Connector

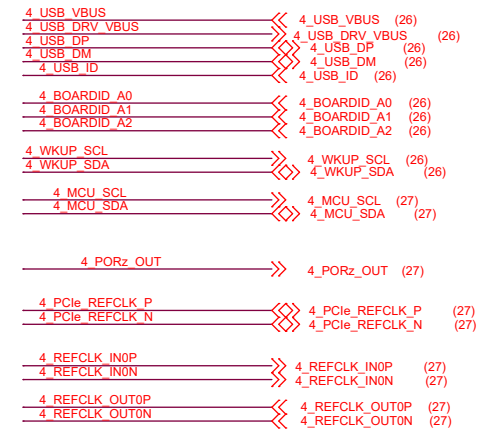
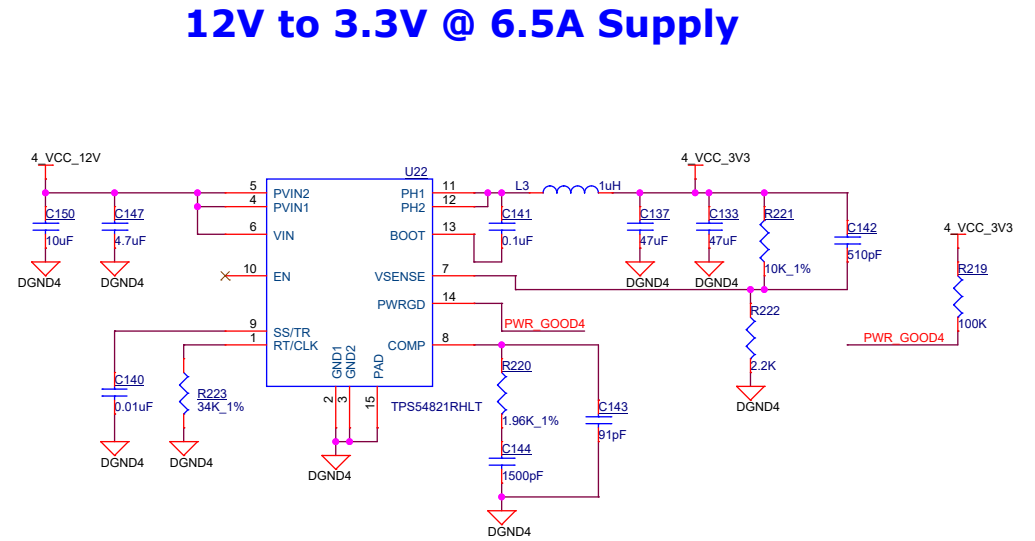
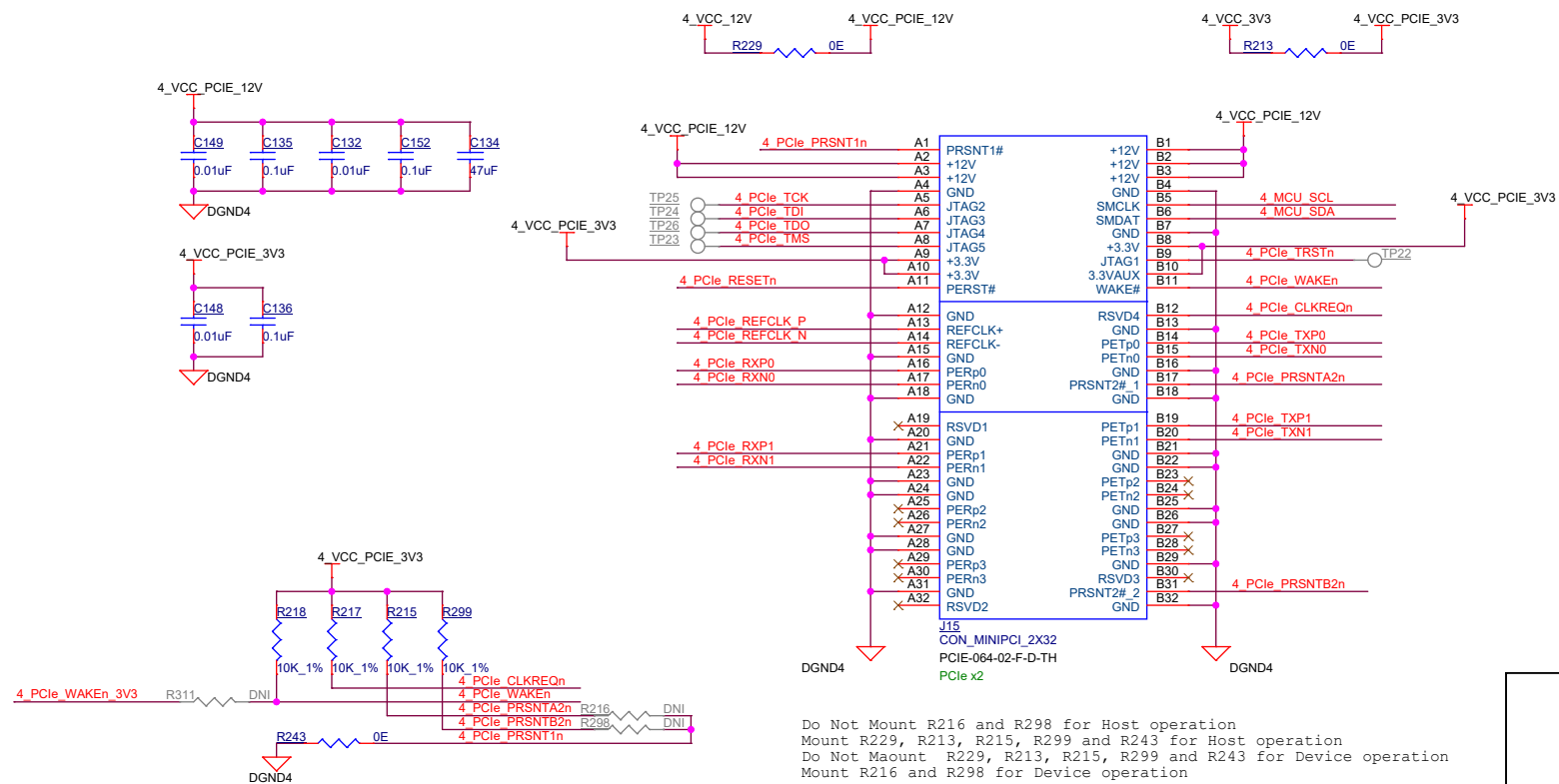


PCIe Reset



Short 1 and 2 for Device operation
Short 3 and 2 for Host operation

x4 Lane PCIe Connector



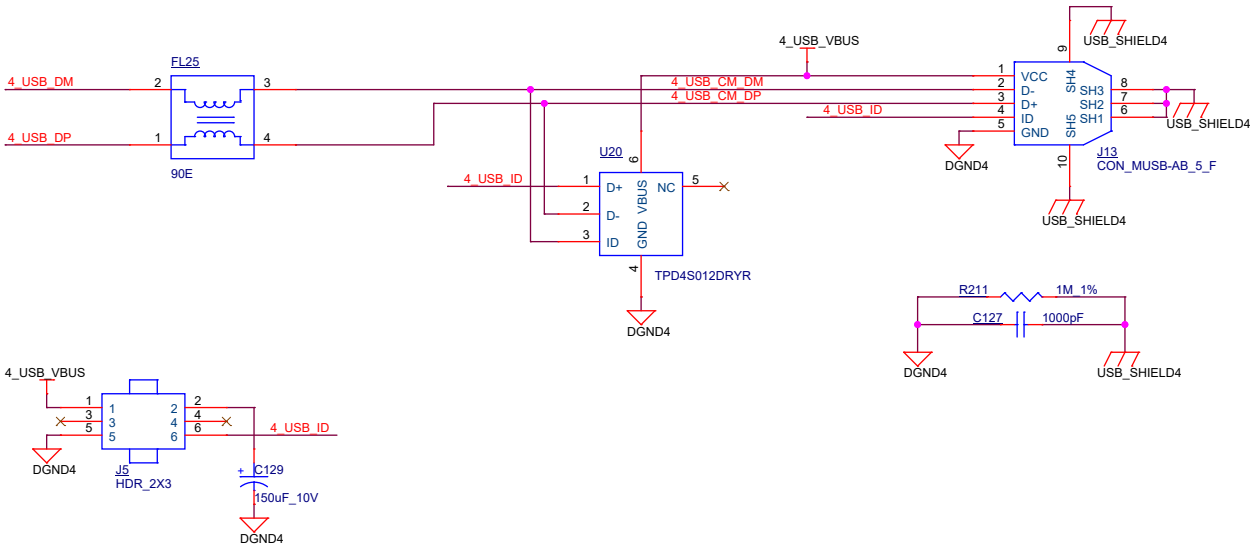
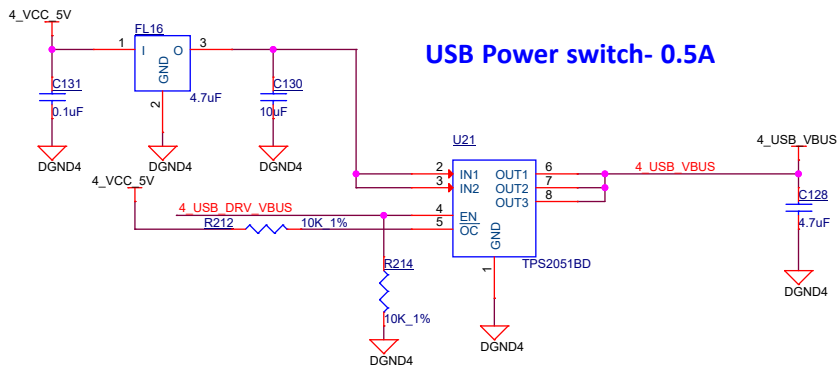
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Title			
2LANEPcie_SERDES & PCIE CON			
Size	PROC067A SER PCIE2LEVM		Rev
C			A
Date:	Friday, March 20, 2020	Sheet	4 of 7

USB 2.0

USB 2.0 micro AB Connector



BOARD ID EEPROM



I2C address: 0x54h or Set by host

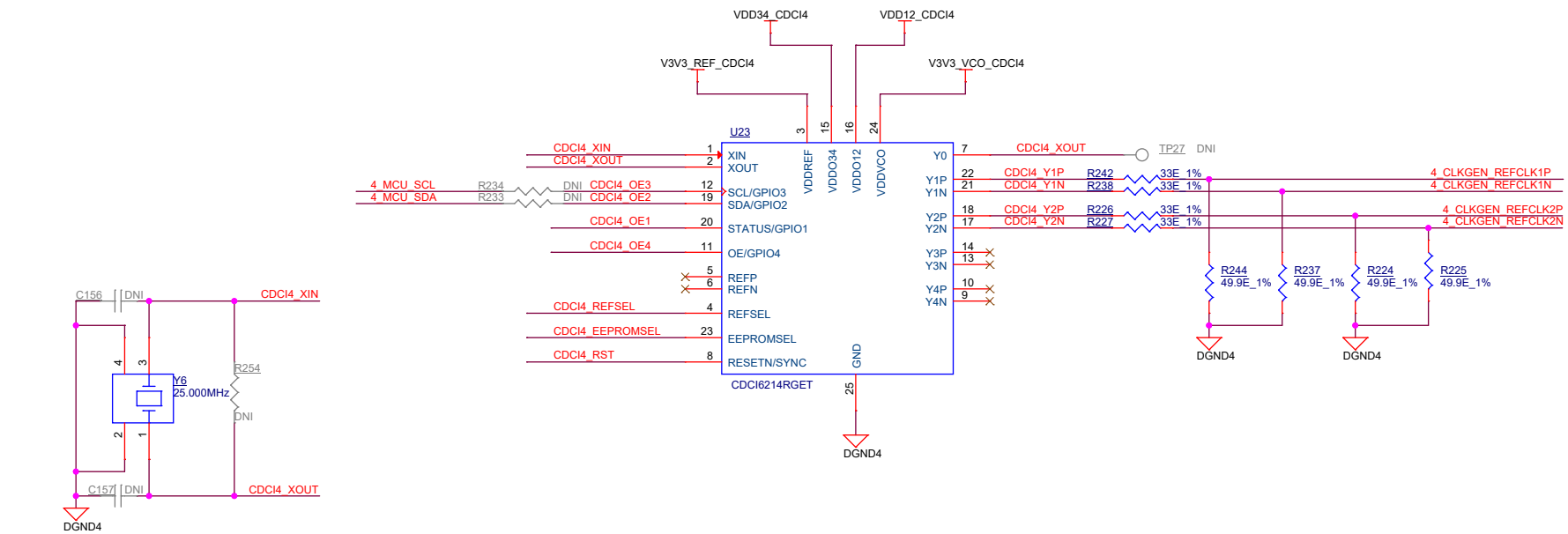
4_BOARDID_A0	>>>	4_BOARDID_A0	(25)
4_BOARDID_A1	>>>	4_BOARDID_A1	(25)
4_BOARDID_A2	>>>	4_BOARDID_A2	(25)
4_USB_ID	>>>	4_USB_ID	(25)
4_USB_VBUS	>>>	4_USB_VBUS	(25)
4_USB_DRV_VBUS	>>>	4_USB_DRV_VBUS	(25)
4_USB_DP	>>>	4_USB_DP	(25)
4_USB_DM	>>>	4_USB_DM	(25)
4_WKUP_SCL	>>>	4_WKUP_SCL	(25)
4_WKUP_SDA	>>>	4_WKUP_SDA	(25)

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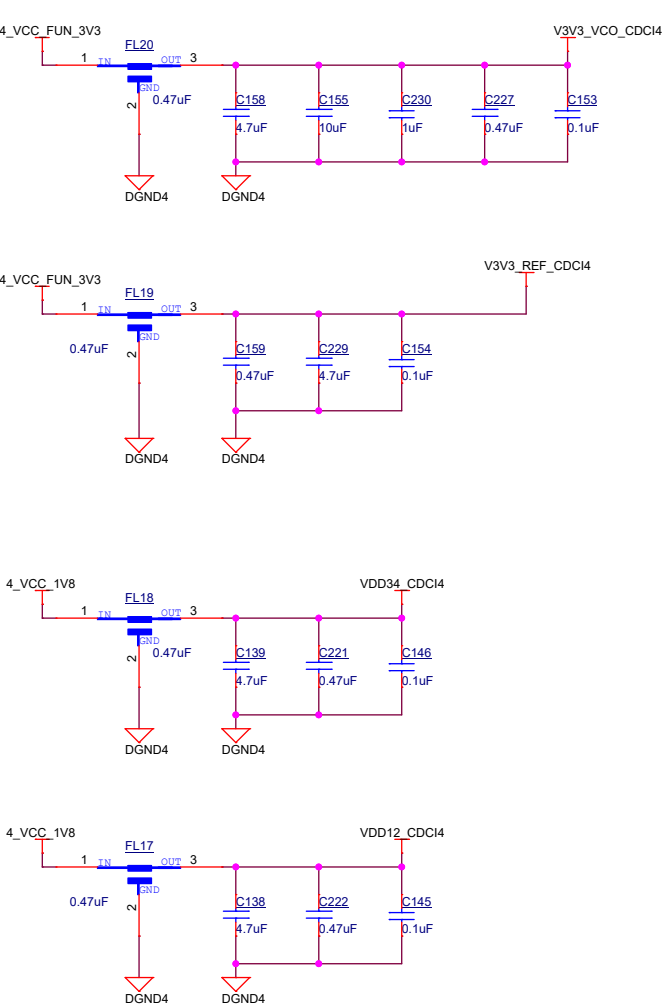
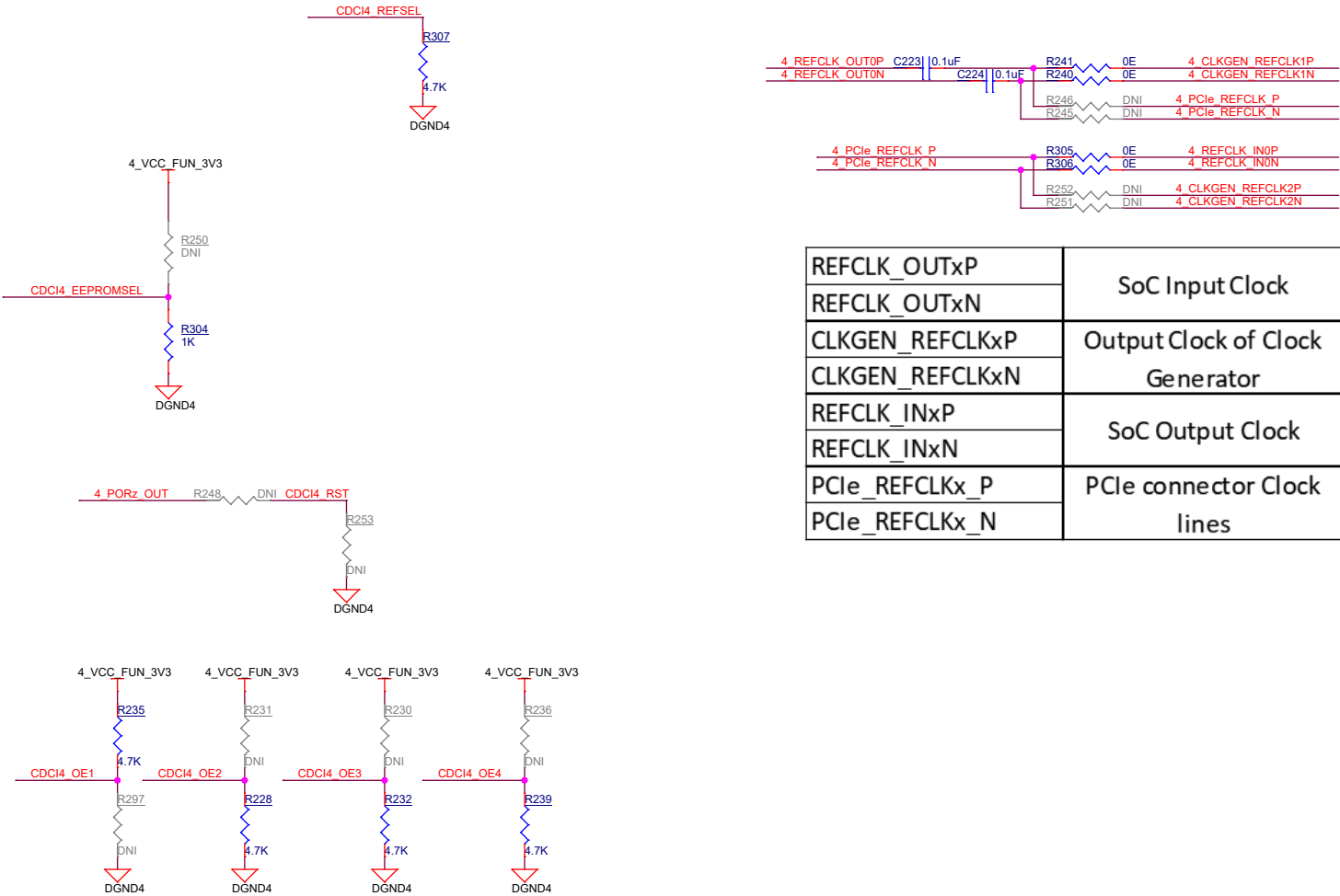


Title			2LANEPCIE_USB2.0 &BRD_ID
Size	PROC067A SER PCIE2LEV	Rev	
C		A	
Date:	Friday, March 20, 2020	Sheet	5 of 7

2 Lane PCIe Clock HCSL (100MHz) (EEPROM PAGE 0)



CLOCK ROOT SELECTION



4 MCU SCL	4 MCU SCL (25)
4 MCU SDA	4 MCU SDA (25)
4 PORz OUT	4 PORz OUT (25)
4 PCIe REFCLK_P	4 PCIe REFCLK_P (25)
4 PCIe REFCLK_N	4 PCIe REFCLK_N (25)
4 REFCLK_IN0P	4 REFCLK_IN0P (25)
4 REFCLK_IN0N	4 REFCLK_IN0N (25)
4 REFCLK_OUT0P	4 REFCLK_OUT0P (25)
4 REFCLK_OUT0N	4 REFCLK_OUT0N (25)

REFCLK_OUTxP	SoC Input Clock
REFCLK_OUTxN	
CLKGEN_REFCLKxP	Output Clock of Clock Generator
CLKGEN_REFCLKxN	
REFCLK_INxP	SoC Output Clock
REFCLK_INxN	
PCIe_REFCLKx_P	PCIe connector Clock lines
PCIe_REFCLKx_N	

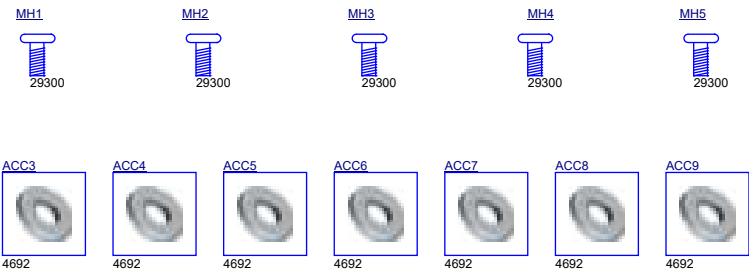
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Title 2LANEPCIE_CLK		
Size C	PROC067A SER PCIE2LEV	Rev A
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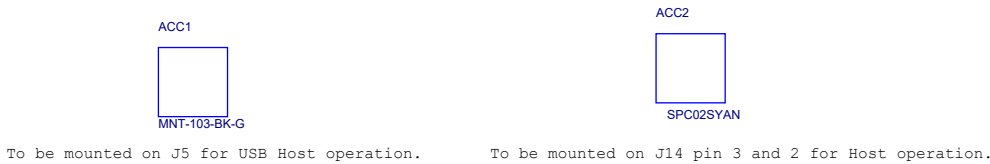
HARDWARE SCHEMATICS

SCREWS and WASHER's

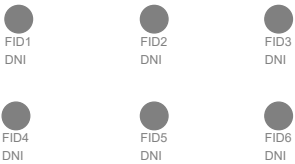


These mechanicals will be used to secure this board to PROC062

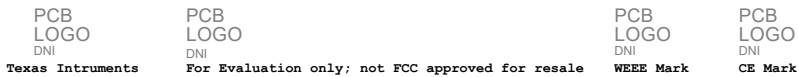
JUMPERs



FIDUCIALS



LOGOs



ASSEMBLY NOTES

1. All MSL components should be baked as per JEDEC standard.
2. PCB should be baked at 120 degree for 8 hours.
3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
4. These assemblies are ESD sensitive, ESD precautions shall be observed.
5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
6. Provide serial numbers to the assembled boards for identification.
7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

LABEL



BARE PCB



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Title
HARDWARE SCHEMATICS

Size
C PROC067A SER PCIe2LEVM

Rev
A

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